



**THE DATASHEET OF
SP2526A-2EN-L/TR**



ABSOLUTE MAXIMUM RATINGS

These are stress ratings only and functional operation of the device at these ratings or any other above those indicated in the operation sections of the specifications below is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

Supply Voltage V_{IN} 7.0V
 Fault Flag Voltage V_{FLG} 7.0V
 Fault Flag Current I_{FLG} 50mA
 Enable Input V_{EN} -0.3V to 15V
 Storage Temperature..... -65°C to 150°C
 Soldering Temperature (10sec) 260°C
 Maximum Junction Temperature..... 125°C
 Power Dissipation (NSOIC-8)
 (derate 6.14mW/°C above 70°C)..... 500mW

OPERATING RATINGS

Ambient Temperature Range..... -40°C to 85°C

ELECTRICAL SPECIFICATIONS

Specifications with standard type are for an Operating Ambient Temperature of $T_A = 25^\circ\text{C}$ only; limits applying over the full Operating Junction Temperature range are denoted by a "•". Minimum and Maximum limits are guaranteed through test, design, or statistical correlation. Typical values represent the most likely parametric norm at $T_A = 25^\circ\text{C}$, and are provided for reference purposes only. Unless otherwise indicated, $V_{IN} = 5.0\text{V}$, $T_A = 25^\circ\text{C}$.

| Parameter | Min. | Typ. | Max. | Units | Conditions |
|-------------------------------------|------|------|------|------------------|--|
| Supply Current | | 0.75 | 5.0 | μA | $V_{EN} = \text{Logic "0"}$ OUT =open |
| | | 110 | 160 | | $V_{EN} = \text{Logic "1"}$ OUT =open |
| Enable Input Voltage | 0.8 | 1.7 | | V | $V_{EN} = \text{Logic "0"}$ |
| | | 2.0 | 2.4 | | $V_{EN} = \text{Logic "1"}$ |
| Enable Input Current | | 0.01 | 1 | μA | $V_{EN} = \text{Logic "0"}$ |
| | | 0.01 | 1 | | $V_{EN} = \text{Logic "1"}$ |
| Enable Input Capacitance | | 1 | | pF | |
| Output MOSFET Resistance | | 110 | 150 | m Ω | |
| Output turn-on delay | | 100 | | μs | $R_L = 10\Omega$, each output |
| Output turn-on rise time | | 1000 | 4000 | μs | $R_L = 10\Omega$, each output |
| Output turn-off delay | | 0.8 | 20 | μs | $R_L = 10\Omega$, each output |
| Output turn-off fall time | | 0.7 | 20 | μs | $R_L = 10\Omega$, each output |
| Output Leakage Current | | | 10 | μA | |
| Current limit threshold | 0.6 | 1.0 | 1.25 | A | |
| Over temperature shutdown threshold | | 135 | | $^\circ\text{C}$ | Temperature T_J raising |
| | | 125 | | | Temperature T_J decreasing |
| Error Flag Output Resistance | | 10 | 25 | Ω | $V_{IN} = 5\text{V}$, $I_L = 10\text{mA}$ |
| | | 15 | 40 | | $V_{IN} = 3.3\text{V}$, $I_L = 10\text{mA}$ |
| Error Flag Current | | 0.01 | 1 | μA | $V_{FLAG} = 5\text{V}$ |
| UVLO threshold | | 2.6 | | V | V_{IN} increasing |
| | | 2.4 | | | V_{IN} decreasing |

BLOCK DIAGRAM

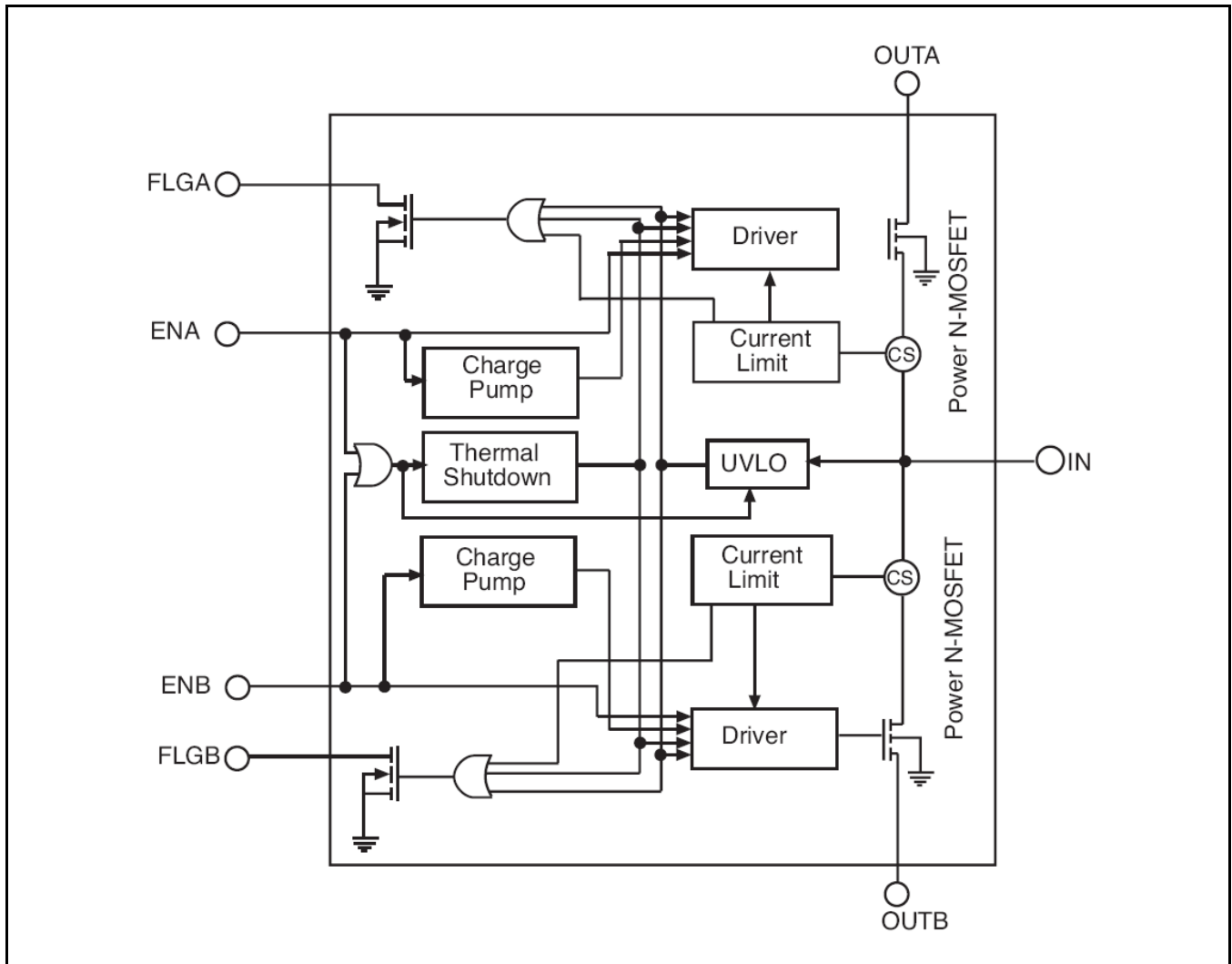


Fig. 2: SP2526A Block Diagram

PIN ASSIGNMENT

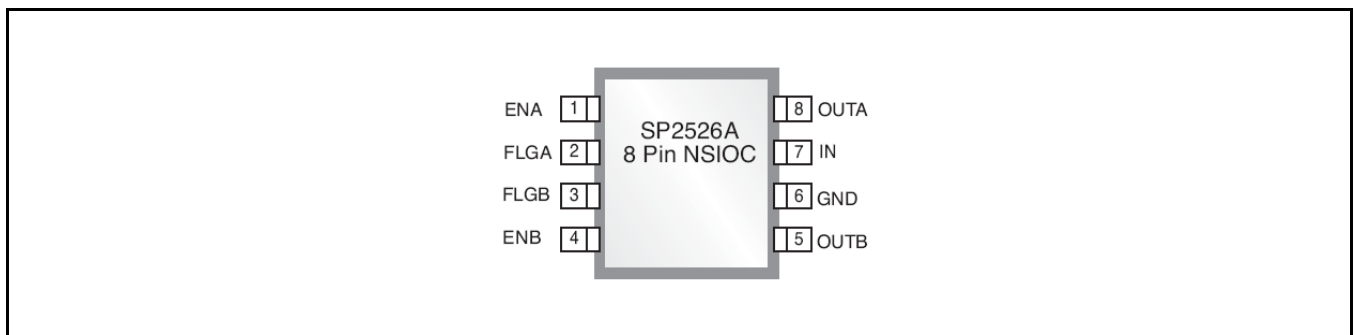


Fig. 3: SP2526A Pin Assignment

**PIN DESCRIPTION**

| Name | Pin Number | Description |
|------|------------|--|
| ENA | 1 | Enable Input for channel A. Active High for SP2526A-1 and Active Low for SP2526A-2 |
| FLGA | 2 | An active-low and open-drained fault flag output for channel A. It can indicate current limit ENA is active. In normal mode operation (ENA and/or ENB is active), it also can indicate thermal shutdown or under voltage |
| FLGB | 3 | An active-low and open-drained fault flag output for channel B. It can indicate current limit ENA is active. In normal mode operation (ENA and/or ENB is active), it also can indicate thermal shutdown or under voltage |
| ENB | 1 | Enable Input for channel B. Active High for SP2526A-1 and Active Low for SP2526A-2 |
| OUTB | 5 | Output for Channel B. This is the output pin of the MOSFET source of channel B, typically connected to the switched side of the load |
| GND | 6 | Ground |
| IN | 7 | Power Supply Input |
| OUTA | 8 | Output for Channel A. This is the output pin of the MOSFET source of channel A, typically connected to the switched side of the load |

ORDERING INFORMATION⁽¹⁾

| Part Number | Temperature Range | Package | Packing Method | Lead Free ⁽²⁾ | Note 1 |
|------------------|---|---------|----------------|--------------------------|--------------------|
| SP2526A-1EN-L/TR | $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ | NSOIC8 | Tape & Reel | Yes | Enable Active High |
| SP2526A-2EN-L/TR | $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ | NSOIC8 | Tape & Reel | Yes | Enable Active Low |

Notes:

1. Refer to www.maxlinear.com/SP2526A for most up-to-date Ordering Information.
2. Visit www.maxlinear.com for additional information on Environmental Rating.

TYPICAL PERFORMANCE CHARACTERISTICS

All data taken at $V_{IN} = 5.0V$, $T_A = 25^\circ C$, unless otherwise specified - Schematic and BOM from Application Information section of this datasheet.

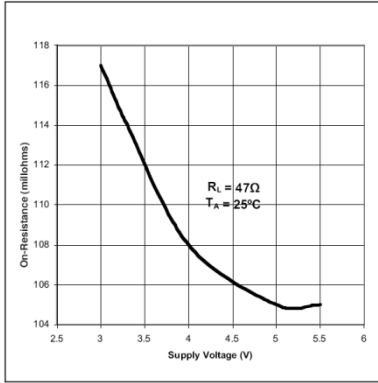


Fig. 4: Output On-Resistance vs Supply Voltage

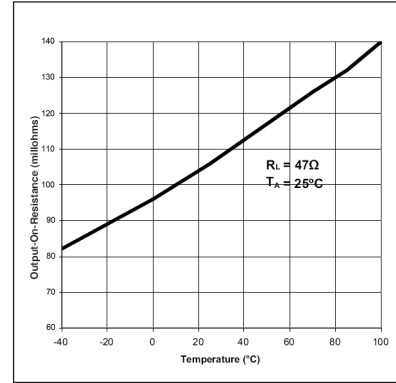


Fig. 5: Output On-Resistance vs Temperature

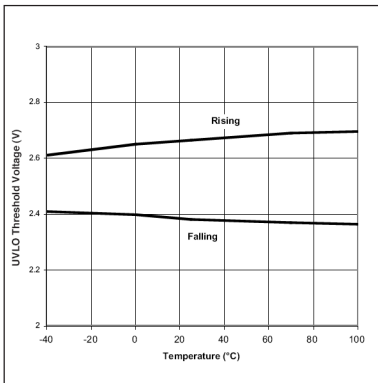


Fig. 6: UVLO Threshold vs Temperature

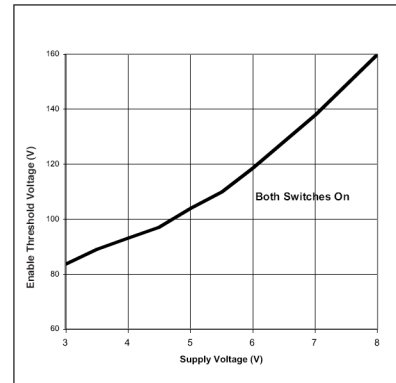


Fig. 7: On-state Supply Current vs Supply Voltage

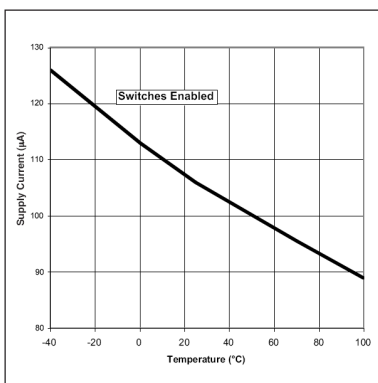


Fig. 8: On-state Supply Current vs Temperature

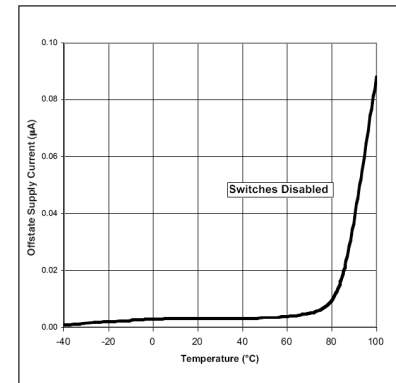


Fig. 9: Off-state Supply Current vs Temperature

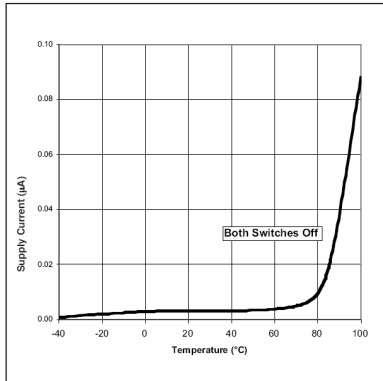


Fig. 10: Off-state Supply Current vs Supply Voltage

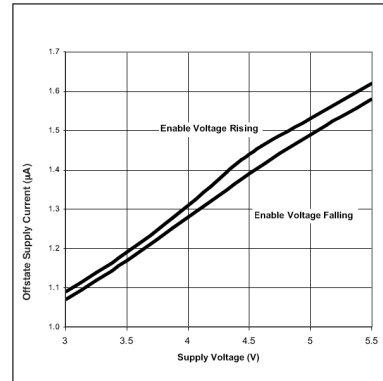


Fig. 11: Control Threshold vs Supply Voltage

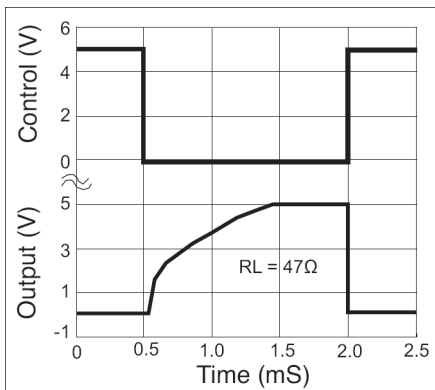


Fig. 12: Turn-on/Turn-off Characteristics

APPLICATION INFORMATION

ERROR FLAG

An open-drained output of an N-channel MOSFET, the FLG output is pulled low to signal the following fault conditions: input undervoltage, output current limit, and thermal shutdown.

CURRENT LIMIT

The current limit threshold is preset internally. It protects the output MOSFET switches from damage resulting from undesirable short circuit conditions or excess inrush current, which is often encountered during hot plug-in. The low limit of the current limit threshold of the SP2526A allows a minimum current of 0.6A through the MOSFET switches. A current limit condition will signal the Error Flag.

THERMAL SHUTDOWN

When the chip temperature exceeds 135°C for any reason other than overcurrent fault of either one of the two MOSFETs, the thermal shutdown function turns off both MOSFET switches and signals the error flag. A hysteresis of 10°C prevents the MOSFETs from turning back on until the chip temperature drops below 125°C. However, if thermal shutdown is triggered by chip temperature rise resulting from overcurrent fault condition of either one of the MOSFET switches, the thermal shutdown function will only turn off the switch that is in overcurrent condition and the other switch can still remain its normal operation. In other words, the thermal shutdown function of the two switches is independent of each other in the case of overcurrent fault.

SUPPLY FILTERING

A 0.1µF to 1µF bypass capacitor from IN to GND, located near the device, is strongly recommended to control supply transients. Without a bypass capacitor, an output short may cause ringing on the input (from supply

lead inductance) which can damage internal control circuitry.

TRANSIENT REQUIREMENTS

USB supports dynamic attachment (hot plugin) of peripherals. A current surge is caused by the input capacitance of a downstream device. Ferrite beads are recommended in series with all power and ground connector pins. Ferrite beads reduce EMI and limit the inrush current during hot-attachment by filtering high-frequency signals.

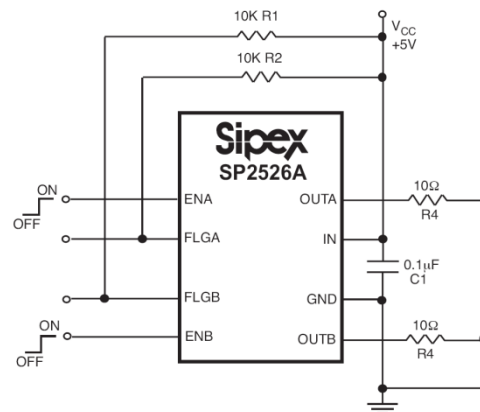
SHORT CIRCUIT TRANSIENT

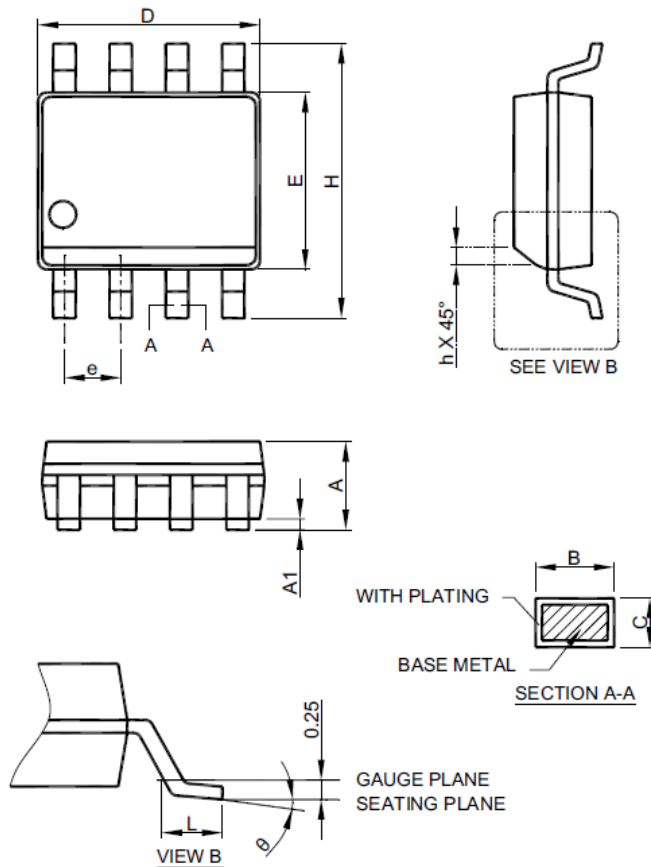
Bulk capacitance provides the short-term transient current needed during a hot-attachment event. A 33µF/16V tantalum or a 100µF/10V electrolytic capacitor mounted close to the downstream connector at each port should provide sufficient transient drop protection.

PRINTED CIRCUIT LAYOUT

The Power circuitry of USB printed circuit boards requires a customized layout to maximize thermal dissipation and to minimize voltage drop and EMI.

TEST CIRCUIT



PACKAGE SPECIFICATION
8-PIN NSOIC


- Note: 1. Refer to JEDEC MS-012AA.
 2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
 3. Dimension "E" does not include inter-lead flash or protrusions.
 4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

| SYMBOL | 8 PIN SOICN | |
|--------|-------------|------|
| | MILLIMETERS | |
| | MIN. | MAX. |
| A | 1.35 | 1.75 |
| A1 | 0.10 | 0.25 |
| B | 0.33 | 0.51 |
| C | 0.19 | 0.25 |
| D | 4.80 | 5.00 |
| E | 3.80 | 4.00 |
| e | 1.27 BSC | |
| H | 5.80 | 6.20 |
| h | 0.25 | 0.50 |
| L | 0.40 | 1.27 |
| theta | 0° | 8° |



REVISION HISTORY

| Revision | Date | Description |
|----------|------------|--|
| 2.0.0 | 11/19/2010 | Reformat of datasheet |
| 2.1.0 | 11/04/2011 | Updated package specification |
| 2.1.1 | 01/22/2020 | Updated to MaxLinear logo. Updated Ordering Information. |



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